828548-3 × OBSOLETE

AMPMODU

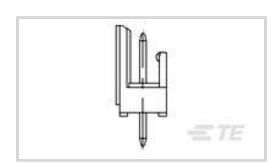
TE Internal #: 828548-3

TE Internal Description: 3P AMP QUICK STLEI

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical
Connector System: Board-to-Board

Number of Positions: 3

Number of Rows: 1

Features

Product Type Features

PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Partially Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Stackable	No
Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Vertical
Number of Positions	3
Number of Rows	1

Electrical Characteristics

Insulation Resistance	1 MΩ	

Body Features

Connector Profile	Standard
Primary Product Color	Natural

Contact Features

Contact Mating Area Length	5.2 mm[.205 in]
Contact Layout	Inline



Mating Pin Diameter	.64 mm[.025 in]
Contact Shape & Form	Round
Contact Base Material	Phosphor Bronze
Contact Mating Area Plating Material	Tin
Contact Mating Area Plating Material Thickness	1.3 µm[51.18 µin]
Contact Type	Pin
Termination Features	
Termination Post & Tail Diameter	.64 mm[.025 in]
Termination Post & Tail Length	2.9 mm[.114 in]
Termination Method to PCB	Through Hole - Solder
Mechanical Attachment	
Mating Retention	With
Mating Alignment	With
Mating Alignment Type	Polarized
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	2.54 mm[.1 in]
Housing Material	PBT GF
Dimensions	
Connector Height	8.8 mm[.34 in]
	1.3 in
Operation/Application	
Solder Process Feature	Board Standoff
Circuit Application	Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	1500
Packaging Mothod	Carton

Carton

Packaging Method



Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 265°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Customers Also Bought























Documents

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_828548-3_E.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_828548-3_E.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_828548-3_E.3d_stp.zip

English

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